

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Johshi GOTOH et al.

Application No.: (Divisional of 10/019,299)

Filed: Herewith

For: UNDERFILLING MATERIAL FOR SEMICONDUCTOR PACKAGE

**PRELIMINARY AMENDMENT**

Mail Stop Patent Application  
Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

Enter the instant amendment before initial examination.

**Amendments to the Claims** begin on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.